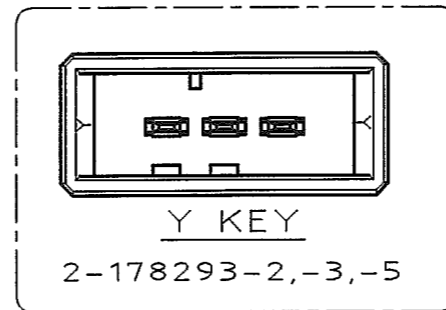
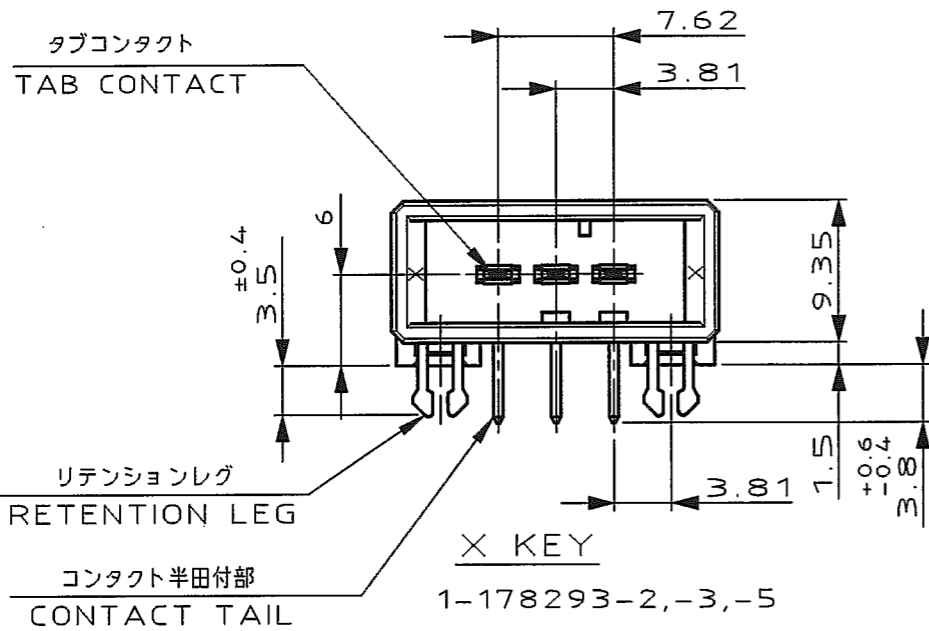
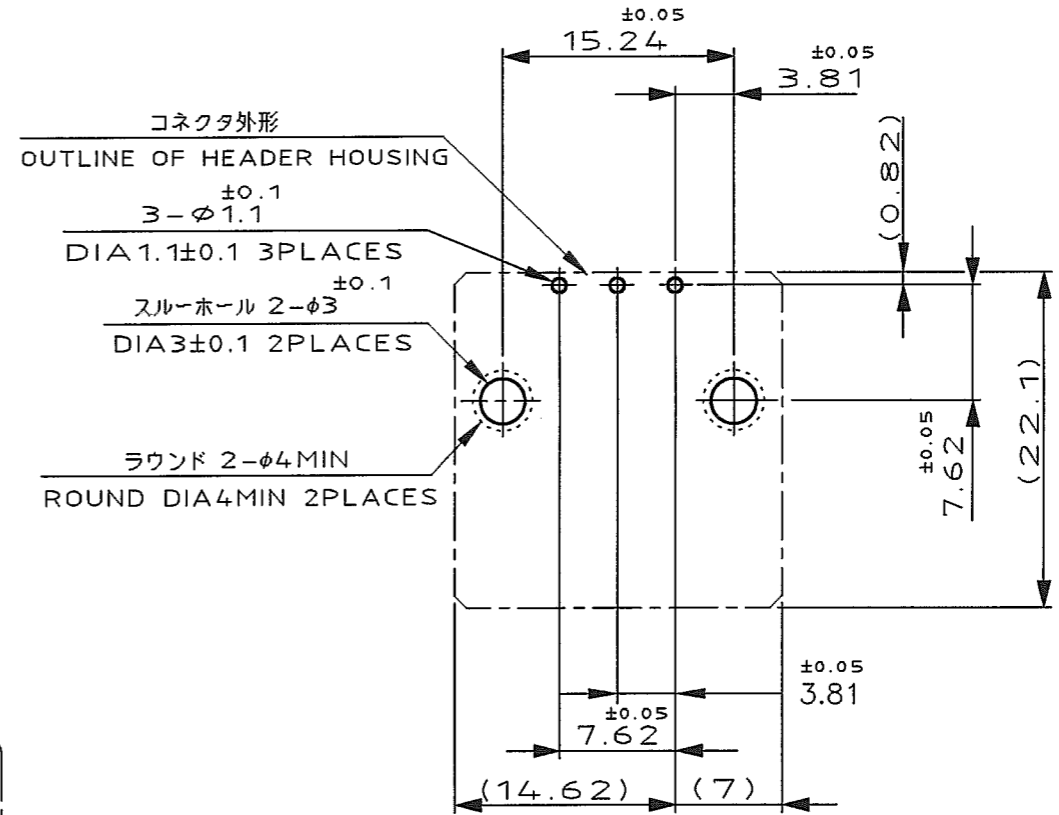
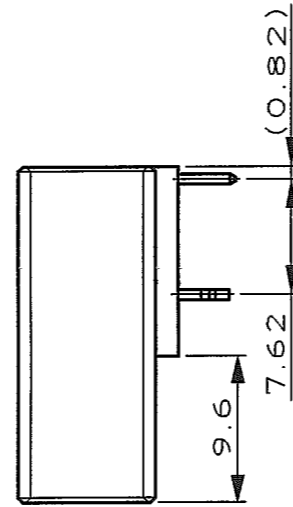
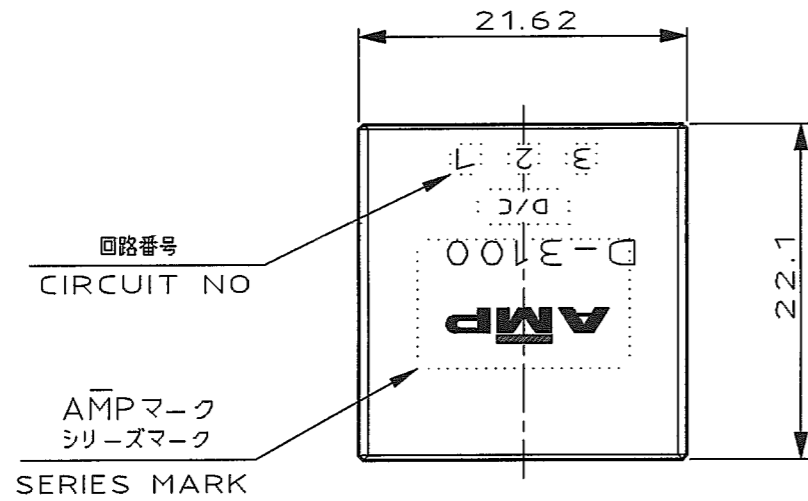


NUMBER 178293
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST



推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- ~~FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- ~~めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき~~
- めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

△6	△4	1,2-178293-5
△6	△3	1,2-178293-3
△6	△2	1,2-178293-2
(FINISH)		製品番号 (PART NO.)

C1	REVISED PER ECO-11-005030	RK	HMR	14 APR 11
LTR	REVISION RECORD	DR	CHK	DATE

DR.	20/MAR/95 K.IKEDA	DE.	20/MAR/95 K.IKEDA
CHK.	23/MAR/92 S.MANABE	APP.	23/MAR/92 S.MANABE

TE Connectivity			
WIRE RANGE mm ² (AWG -)			
INSULATION DIA mmφ			
NAME 3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100			
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照	
一般公差 (GENERAL TOLERANCE) 10mmF : ±0.3 10mmE 3mmF : ±0.4 30mmE 100mmF : ±0.5 角度 : ±3°		SIZE A3	LOC J
NUMBER C= 178293		SCALE 2-1	REV. C1
SHEET 1 OF 1			

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[2-178293-2](#)